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December 16, 2002

TO: Commissioner for Patents  
Attn: Andy Huynh  
Patent Examining Corps  
Facsimile Center  
Washington, D.C. 20231

FROM: Walter W. Nielsen

OUR REF: 884,319US1

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**FAX NUMBER (703) 308-7724**

\* Please deliver to Examiner Andy Huynh in Art Unit 2818. \*

Document(s) Transmitted: Amendment and Response Under 37 CFR 1.111; Clean Version of Amended Specification Paragraphs; Clean Version of Pending Claims

Total pages of this transmission, including cover letter: 21

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In re Patent Application of: Biswajit Sur et al.

Examiner: Andy Huynh

Serial No.: 09/652,430

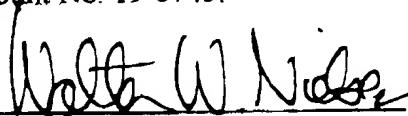
Group Art Unit: 2818

Filed: August 31, 2000

Docket No.: 884,319US1

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE

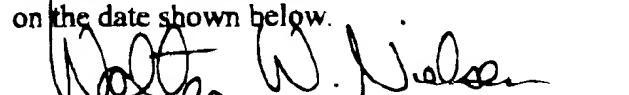
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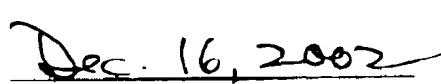
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Reg. No.: Reg. No. 25,539

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Walter W. Nielsen

  
Dec. 16, 2002

Date of Transmission

*FF8/Smclt B*  
*Patent Filed  
11/11/03*

S/N 09/652,430

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Biswajit Sur et al.

Examiner: Andy Huynh

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INTERFACE

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**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Applicants have reviewed the Office Action mailed on September 16, 2002. Please amend the above-identified patent application as follows.

**IN THE SPECIFICATION**

Please make the paragraph substitutions indicated in the appendix entitled "Clean Version of Amended Specification Paragraphs". The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs.

The sub-title on page 1, line 8 is amended as follows: Technical Field [of the Invention]

The paragraph beginning on page 1, line 10 is amended as follows:

Embodiments of the [The] present invention relate [relates] generally to electronics packaging. More particularly, the present invention relates to an electronic assembly that includes an integrated circuit package comprising a solderable thermal interface between the integrated circuit and a heat spreader to dissipate heat generated in a high speed integrated circuit, and to manufacturing methods related thereto.

The sub-title on page 1, line 16 is amended as follows: Background Information [of the Invention]